CICMT Program Grid

Sunday, April 10

4 pm – 7 pm	**Registration**
5 pm - 6 pm	**Frontier of Science and Society - Rustum Roy Lecture** **Speaker: Dr. Arden L. Bement, Jr., National Institute of Standards and Technology**
6 pm - 7 pm	**Welcome Reception**

Monday, April 11

7 am – 5 pm	**Registration**
8:30 am – 9:30 am	**Keynote Presentation** **Title: Future Challenges and Opportunities in Multilayer Ceramic Technology** **Speakers: Clive A. Randall, G. Yang, E. Dickey, R. Eitel, K. Rajab, M. Iwaski, E. Semouchkina, G. Semouchkina, A. Baker, S. Rhee, K. Uchino, M. J. Lanagan, Pennsylvania State University**
9:30 am – 10:30 am	**Keynote Presentation** **Title: Current and Future Directions for Ceramic Interconnect** **Speakers: Christian Hoffmann, Sebastian Brunner, Markus Noren, EPCOS OHG**
11 am - Noon	**Edward Orton, Jr. Memorial Lecture** **Speaker: Dr. Peter Barnwell, Custom Interconnect (CIL)**
Noon - 1 pm	**Lunch**
1 pm - 1:55 pm	**Keynote Presentation** **Title: Materials Process and Manufacturing: Current and Future Directions** **Speaker: Andreas Roosen, University of Erlangen – Nuremberg**

	Ceramic Micro Systems Track	Ceramic Interconnect Track
Topical Sessions: 2 pm - 3:20 pm	**Session MP1: Materials Solution for Microsystems** **Chair: Heiko Thust, Technical Univ. of Ilmenau**	**Session MP2: Cofiring** **Chairs: Fred Barlow, University of Arkansas; Martin Oppermann, EADS Deutschland GmbH**
3:20 pm - 3:40 pm	**Break**	
Topical Session: 3:40 pm - 5 pm	**Session MP3: Microsystem Materials & Integration** **Chair: Bob Freer, University of Manchester/UMIST**	**Session MP4: Dimensional Control in LTCC Systems** **Chairs: Adam Schubring, Visteon Corporation; Walter Rothlingshofer, Robert Bosch GmbH**

Tuesday, April 12

7 am - 8 pm	**Registration**
5 pm - 8 pm	**Exhibit Hours**
8 am - 8:55 am	**Keynote Presentation** **Title: Ceramic Microsystems for Automotive Applications** **Speaker: Gerhard Schneider, Robert Bosch GmbH**

Topical Sessions: 9 am - 10:20 am	**Session TA1: Ceramic Microsystems and Applications I** **Chair: Leszek Golonka, Wroclaw University of Technology**	**Session TA2: Processing Integrated Passives in LTCC** **Chair: Raghu Settaluri, Oregon State University**
10:20 am - 10:40 am	**Break**	
Topical Sessions: 10:40 am - Noon	**Session TA3: Ceramic Microsystems and Applications II** **Chair: Amy Moll, Boise State University**	**Session TA4: Materials Integration in LTCC** **Chair: Larry Zawicki, Honeywell Federal Manufacturing and Technologies, LLC**

1:30 pm - 4:30 pm	**Global Business Council (GBC)** **Business of Emerging Microsystems** **Chairs: Michael O'Neill, Heraeus Incorporated-Circuit Materials Division;** **Michael Lanagan, The Pennsylvania State University** **Panel Discussion** **Moderator: David Wilcox, Consultant**
5 pm - 8 pm	**Reception/Dinner in the Exhibit Hall**

Wednesday, April 13

7 am - 5 pm	**Registration**
10 am - 2 pm	**Exhibit Hours**
8 am - 8:55 am	**Keynote Presentation** **Title: Integrated Design and Simulation Tools for Microsystems Packaging: Current Capabilities and Future Needs** **Speaker: Marc Desmulliez, Heriot Watt University**

Topical Sessions: 9 am - 10:20 am	**Session WA1: Design and Fabrication of Ceramic Microsystems and Devices** **Chair: Torsten Rabe, Federal Institute for Materials Research and Testing**	**Session WA2: Design, Simulation and Modeling** **Chair: Daniel Amey, DuPont Microcircuit Materials**
10:20 am -10 40 am	**Break**	
Topical Sessions: 10:40 am - Noon	**Session WA3: Ceramic Microsystems and Devices** **Chair: Klaus-Dieter Lang, Fraunhofer IZM**	**Session WA4: Characterizing Materials Integration Effects** **Chair: Daniel Krueger, Honeywell FM&T**

Noon - 1 pm	**Lunch in Exhibit Hall**
1 pm - 1:55 pm	**Keynote Presentation** **Title: Next-Generation Microsystems: Integration Technologies and Opportunities for Ceramics** **Speaker: Duane Dimos, Sandia National Laboratories**

Topical Sessions: 2 pm - 3:20 pm	**Session WP1: Ceramics: The Microsystem Device Enabler** **Chair: Paul Clem, Sandia National Laboratories**	**Session WP2: Ink Jet Printing Technology** **Chairs: Veena Tikare, Sandia National Laboratories; Tom Swiler, Sandia National Laboratories**
3:20 pm - 3:40 pm	**Break**	
Topical Session: 3:40 pm - 5 pm	**Session WP3: Microsystem Materials and Fabrication** **Chair: Dean Anderson, TRS Ceramics, Inc. and The Pennsylvania State University**	